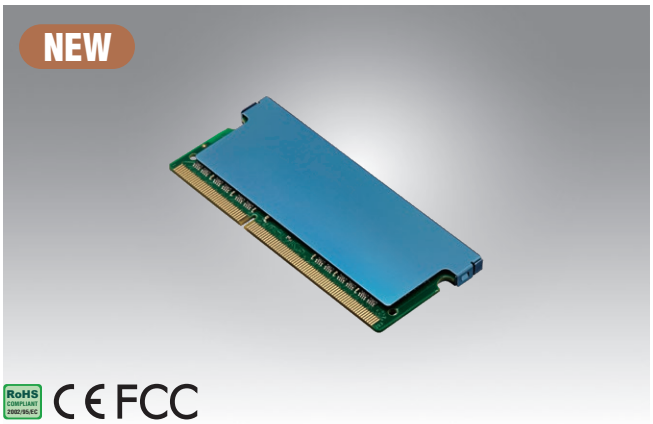
SQR-HS3N
Heatsink series



Features

- Original Samsung, Micron DRAM IC adopted
- Data Transfer Rate: 1600 MT/s
- Heatsink attached
- Thermal sensor attached
- Fixed BOM

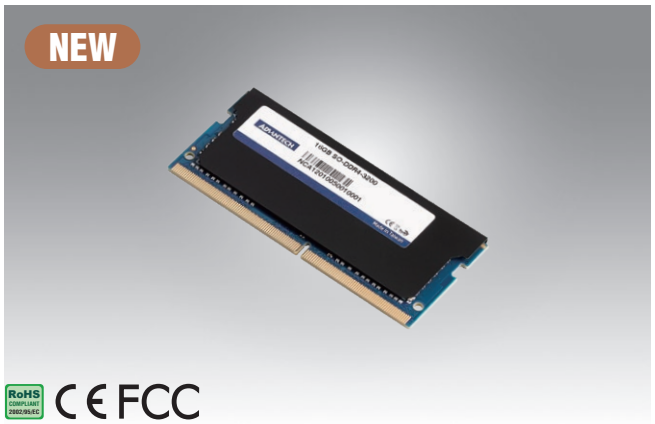
Specifications

DDR Type	DDR3L
Pin / DIMM	204pin SODIMM
Data Transfer Rate	1600 MT/s
Golden Finger	30u"
Capacity	4GB/ 8GB
Power Supply	1.35V / 1.5V
Operating Temperature	-40 ~ 85 °C
Dimensions (mm)	67.6 x 30 ± 0.15

Ordering Information

PN	Description
SQR-HS3I-4G1K6SNLB	HEATSINK 204pin SODIMM DDR3L 1600 4GB 1.35v 512x8 (-40 ~ 85 °C) SAM
SQR-HS3I-8G1K6SNLB	HEATSINK 204pin SODIMM DDR3L 1600 8GB 1.35v 512x8 (-40 ~ 85 °C) SAM
SQR-HS3I4G1K6MNEPB	HEATSINK 204pin SODIMM DDR3L 1600 4GB 1.35v 512x8 (-40 ~ 85 °C) MIC
SQR-HS3I8G1K6MNEPB	HEATSINK 204pin SODIMM DDR3L 1600 8GB 1.35v 512x8 (-40 ~ 85 °C) MIC

SQR-HS4N
Heatsink series



Features

- Original Samsung DRAM IC adopted
- Data Transfer Rate: 2666/3200 MT/s
- Anti-sulfuration DRAM module
- Heatsink/Thermal sensor attached
- Fixed BOM

Specifications

DDR Type	DDR4
Pin / DIMM	260pin SODIMM with ECC
Data Transfer Rate	2666/3200 MT/s
Golden Finger	30u"
Capacity	16GB ~ 32GB
Power Supply	1.2V (1.26V~1.14V)
Operating Temperature	0 ~ 85/-40 ~ 85 °C
Dimensions (mm)	69.6 x 30 ± 0.13

Ordering Information

PN	Description
SQR-HS4I16G3K2SECB	Heatsink 240pin ECC SODIMM DDR4 3200 16GB 1.2v 1Gx8 (-40 ~ 85 °C) SAM
SQR-HS4I32G3K2SEAB	Heatsink 260pin ECC SODIMM DDR4 3200 32GB 1.2v 2Gx8 (-40 ~ 85 °C) SAM
SQR-HS4N16G3K2SECB	Heatsink 240pin ECC SODIMM DDR4 3200 16GB 1.2v 1Gx8 (0 ~ 85 °C) SAM
SQR-HS4N32G3K2SEAB	Heatsink 260pin ECC SODIMM DDR4 3200 32GB 1.2v 2Gx8 (0 ~ 85 °C) SAM

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